

GODDARD SPACE FLIGHT CENTER

Test Lab Report Summary

<i>Report Number:</i>	Q10150DPA	<i>Project:</i>	SWIFT
<i>Part Type:</i>	Microcircuit	<i>System:</i>	BAT
<i>Part Number:</i>	AD780BR	<i>Initiated Date:</i>	05/02/2001
<i>Date Code:</i>	0037	<i>Report Date:</i>	09/21/2001
<i>Manufacturer:</i>	Analog Devices, Inc.	<i>Investigator:</i>	C. Greenwell (562)
<i>Generic Number:</i>	AD780	<i>Requester:</i>	B. Meinhold (562)
<i>Purchase Spec:</i>	Commercial	<i>Approval / Date:</i>	

Step 1: INCOMING INSPECTION

<u>Test</u>	<u>Quantity</u>	<u>Passed</u>	<u>Failed</u>
External Visual	N/A	N/A	N/A
PIND Condition A	N/A	N/A	N/A

Step 2: DESTRUCTIVE PHYSICAL ANALYSIS

Destructive Physical Analysis (DPA) was conducted per GSFC document “Plastic Encapsulated Microcircuit (PEM) Guidelines for Screening and Qualification for Space Applications”, except that cross-section was done without dye penetrant and glassivation integrity testing was not performed.

No rejectable defects or anomalies were observed during this analysis.

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Summary of Analysis:

	<i>Serial Number</i>	<u>C14</u>	<u>C15</u>	<u>D16</u>	<u>D17</u>	<u>D18</u>
<i>External Examination</i>						
1. Markings - legibility and correctness _____		A	A	A	A	A
2. Integrity of package seals _____		N/A	N/A	N/A	N/A	N/A
3. Condition of external leads and plating _____		A	A	A	A	A
4. Overall package condition _____		A	A	A	A	A
<i>Radiographic Examination</i>						
5. Die bonding material and die alignment _____		A	A	A	A	A
6. Package seal integrity _____		N/A	N/A	N/A	N/A	N/A
7. Presence of foreign material _____		A	A	A	A	A
8. Lead dress (if revealed) _____		A	A	A	A	A
<i>Acoustic Microscopy Inspection</i>						
9. Condition of material interfaces (delaminations) _____		A	A	A	A	A
10. Condition of molding material (voids, cracks) _____		A	A	A	A	A
<i>Internal Examination (including cross-section)</i>						
11. Presence of foreign material _____		A	A	A	A	A
12. Mechanical condition of die _____		A	A	A	A	A
13. Wire bonds and lead dress _____		N/P	N/P	A	A	A
14. Die bonding material _____		A	A	A	A	A
15. Condition of die surface _____		N/P	N/P	A	A	A
16. Condition of metallization _____		N/P	N/P	A	A	A
17. SEM Examination _____		A	A	A	A	A
<i>Bond Strength</i>						
18. Strength _____		N/P	N/P	A	A	A
19. Metallization adherence _____		N/P	N/P	A	A	A
<i>Die Bond Strength</i>						
20. Strength _____		N/P	N/P	N/P	N/P	N/P

SN's C14 and C15 subjected to cross-sectional examination.

(* = Refer to comments, A = acceptable, U = unacceptable, N/A = not applicable, N/P = not performed)

Appended Photographs:

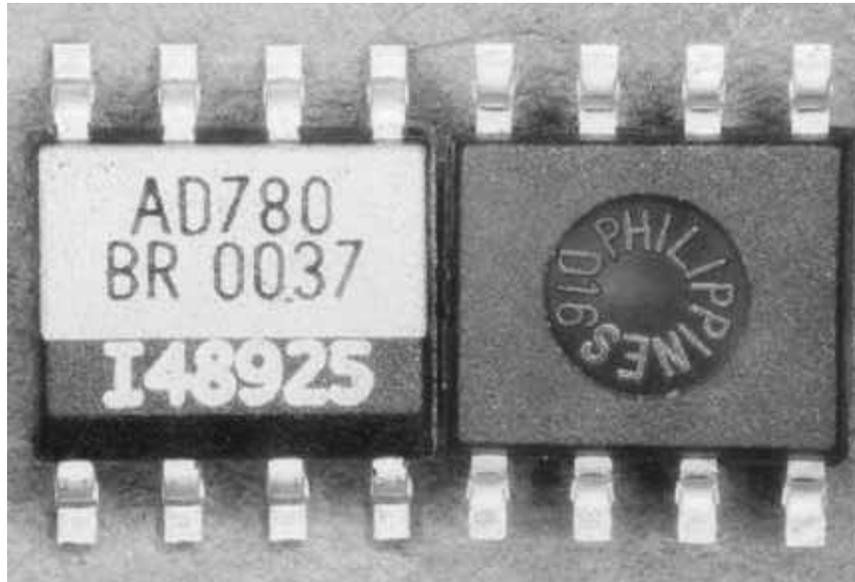


Figure 1. External top and bottom views of the AD780BR devices. 12X

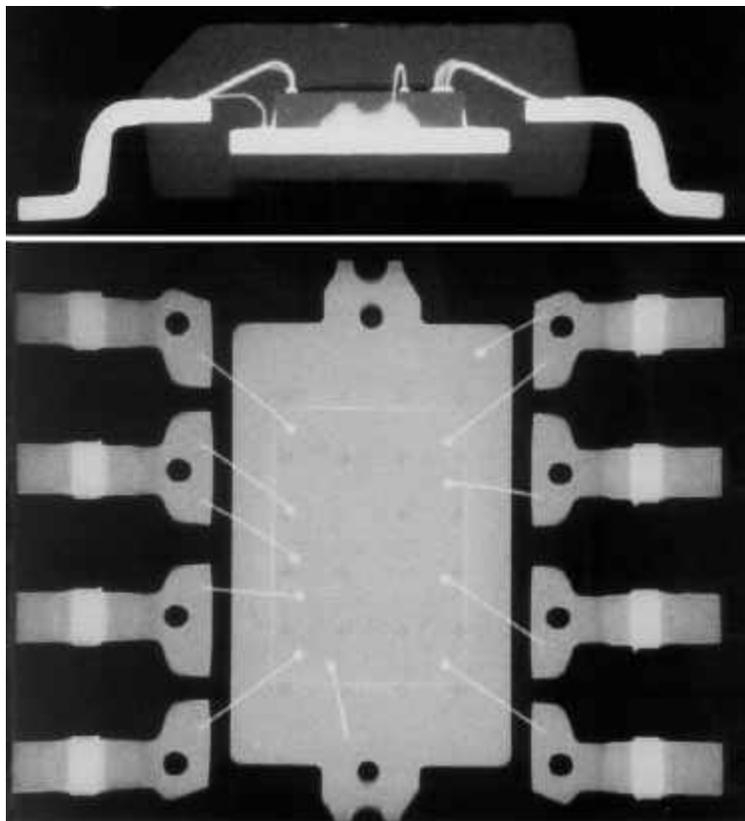


Figure 2. Top and side view radiographic images. The side view image (top) shows the die is glob-topped. 14X

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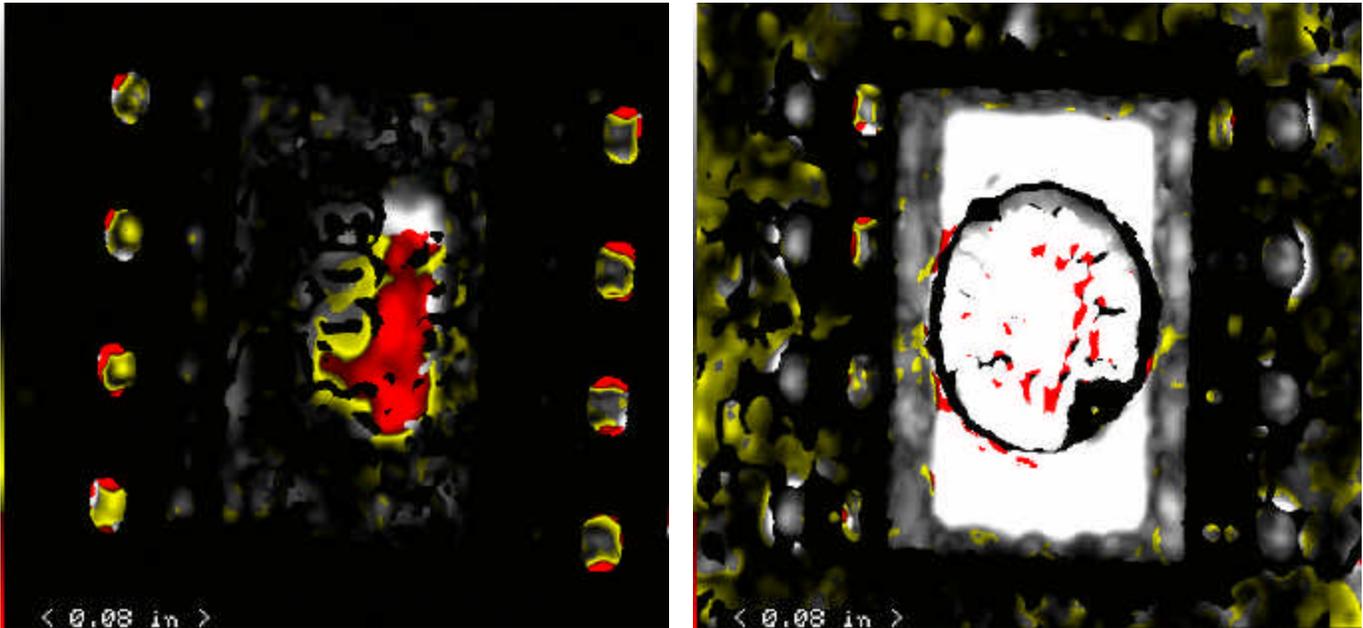


Figure 3. Top (left) and bottom C-SAM images of SN C14. The die glob-top material and device part markings produce artifact in the image. This does not indicate delamination.

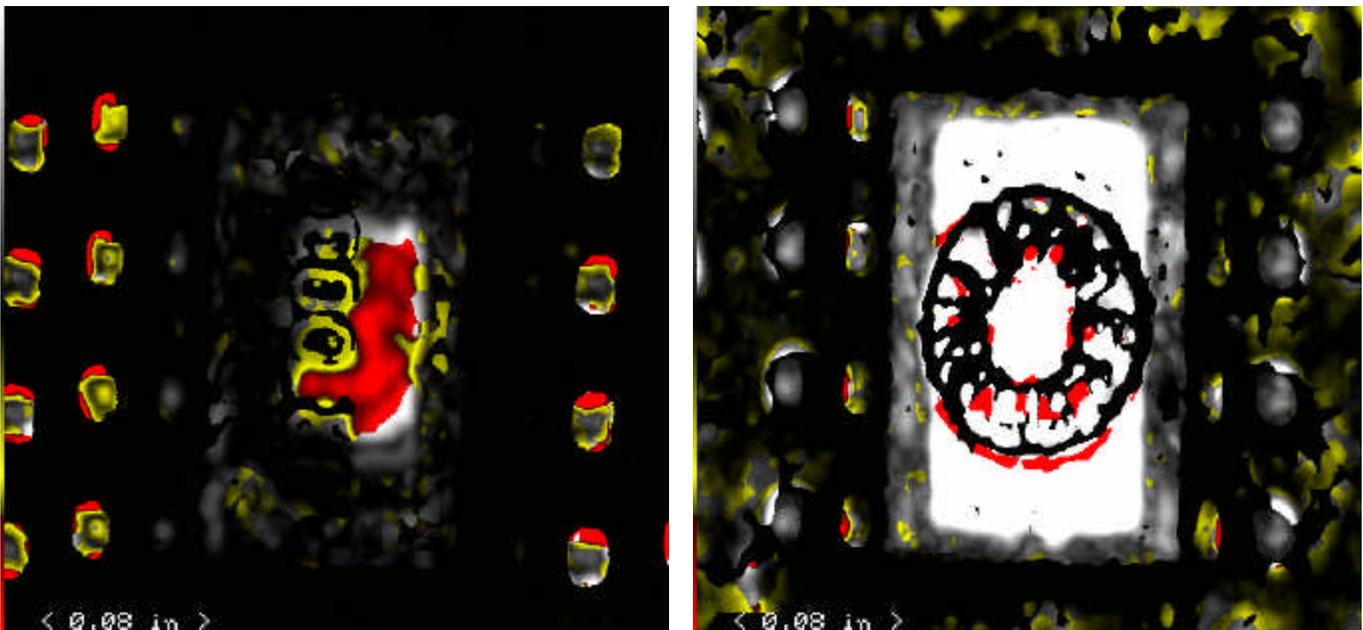


Figure 4. Top (left) and bottom C-SAM images of SN C15.

Appended Photographs:

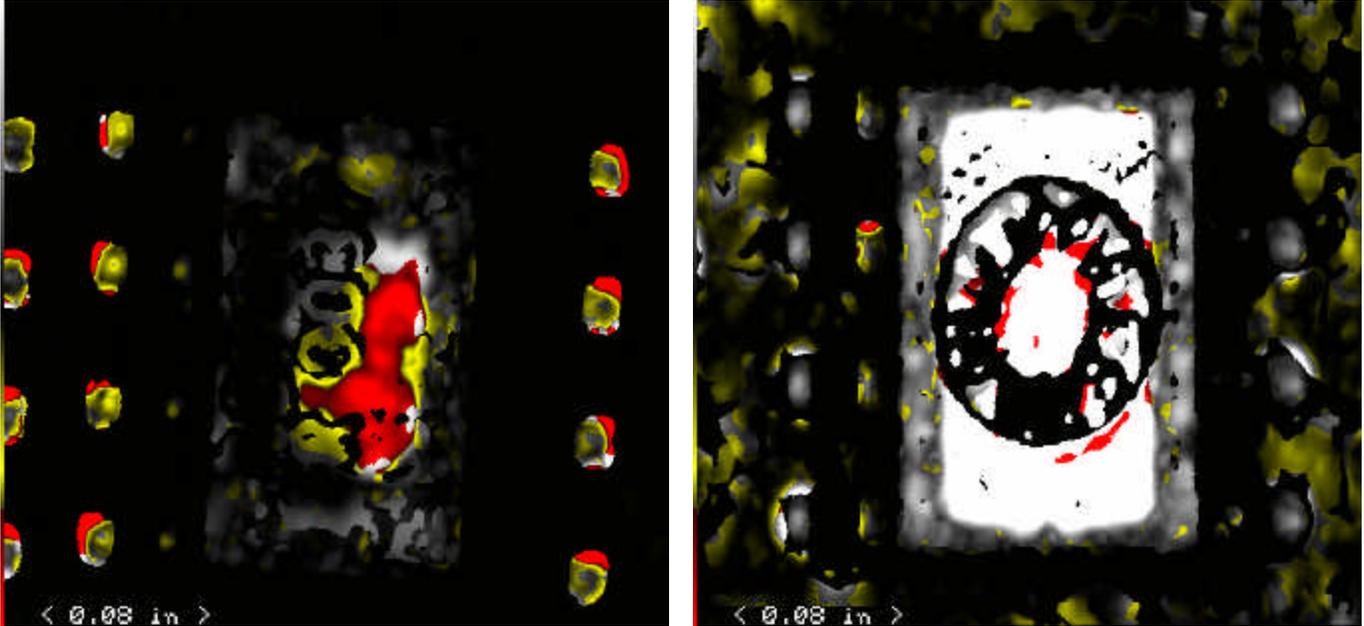


Figure 5. Top (left) and bottom C-SAM images of SN D16.

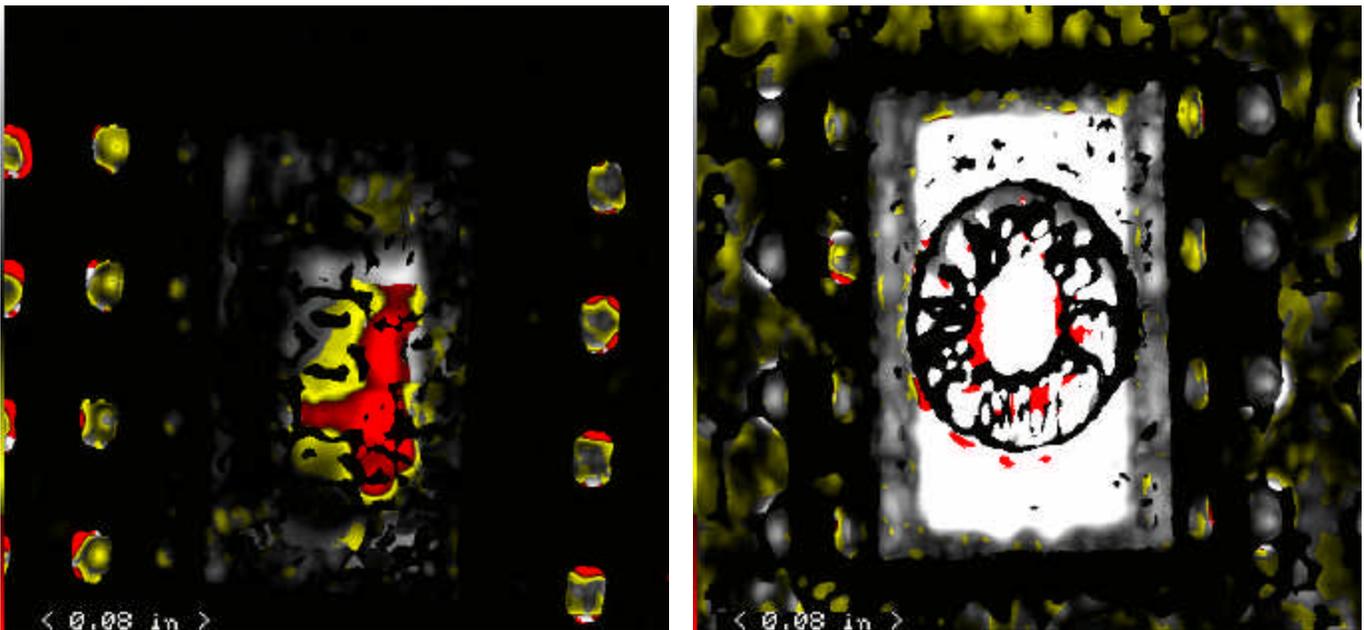


Figure 6. Top (left) and bottom C-SAM images of SN D17.

Appended Photographs:

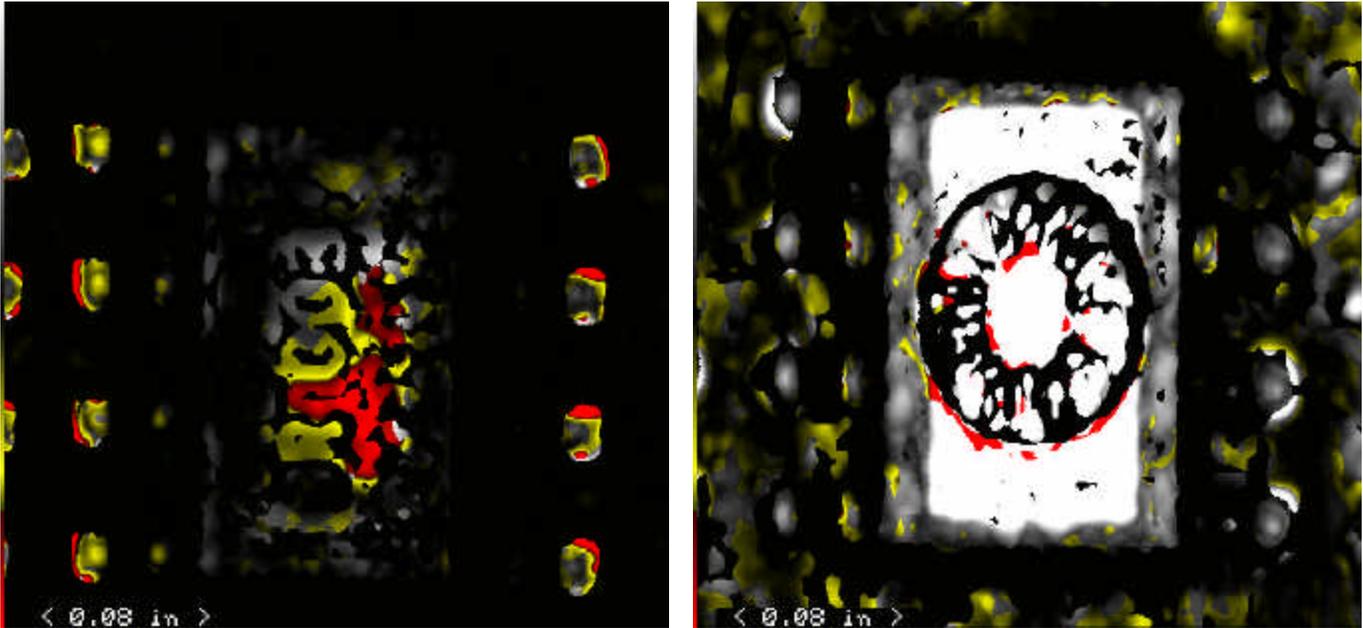


Figure 7. Top (left) and bottom C-SAM images of SN D18.

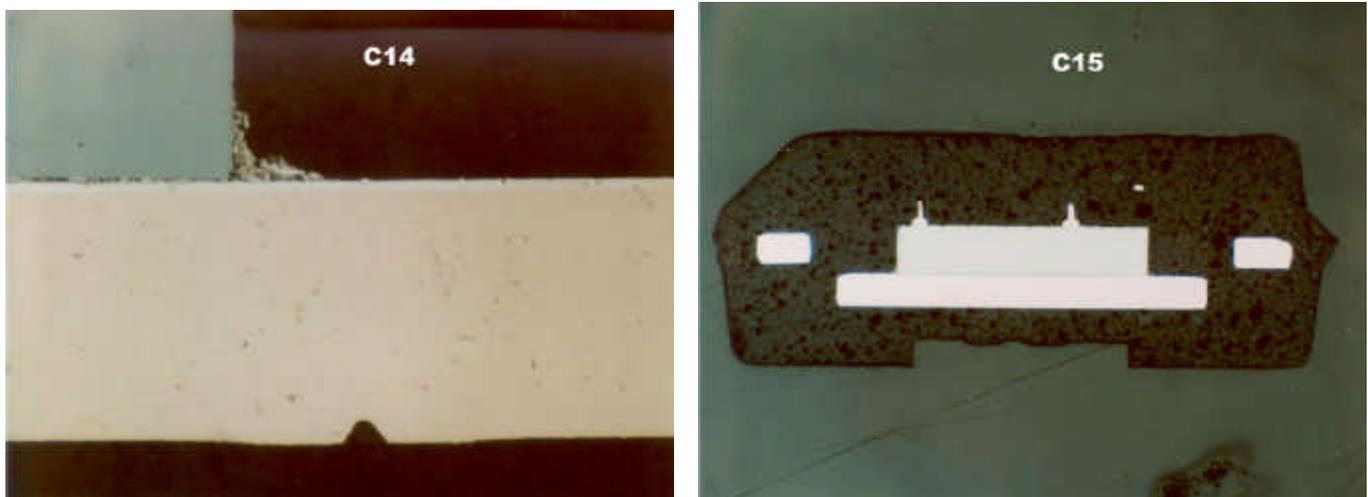


Figure 8. Cross-section images of SN C14 and SN C15. The image of C15 is taken at a section plane just at the edge of the die; the glob-top material is not yet visible. Left image - 200X; right image - 25X

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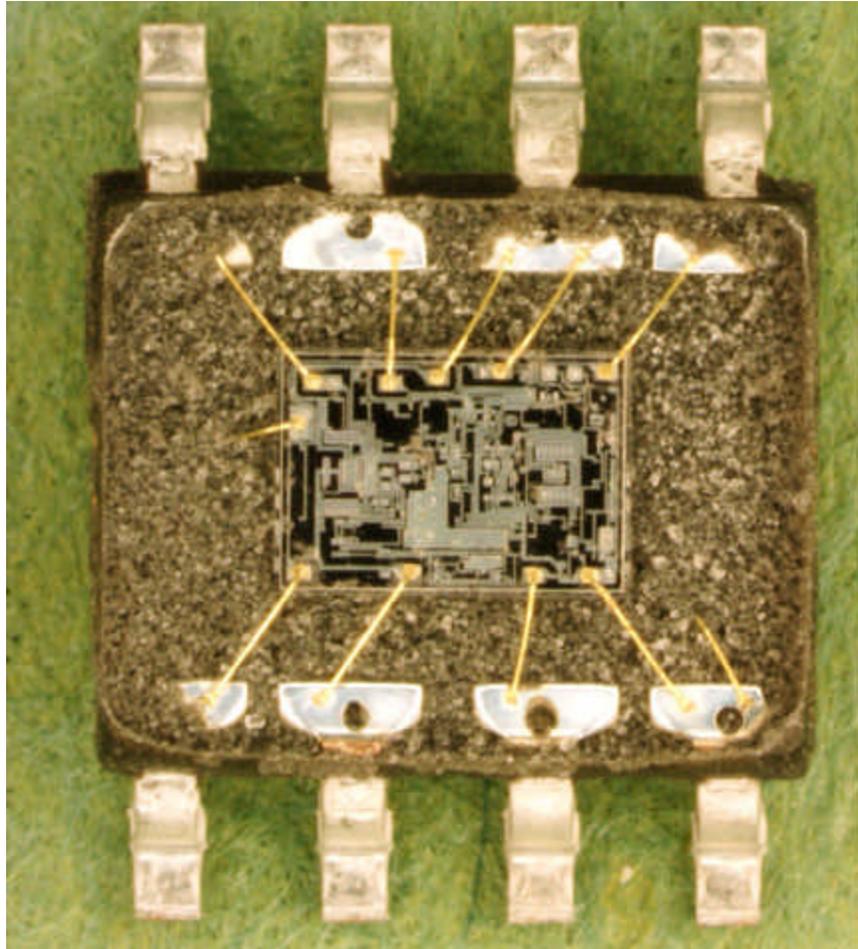


Figure 9. Overall view of SN D16 deprocessed for internal examination and wire pull testing.

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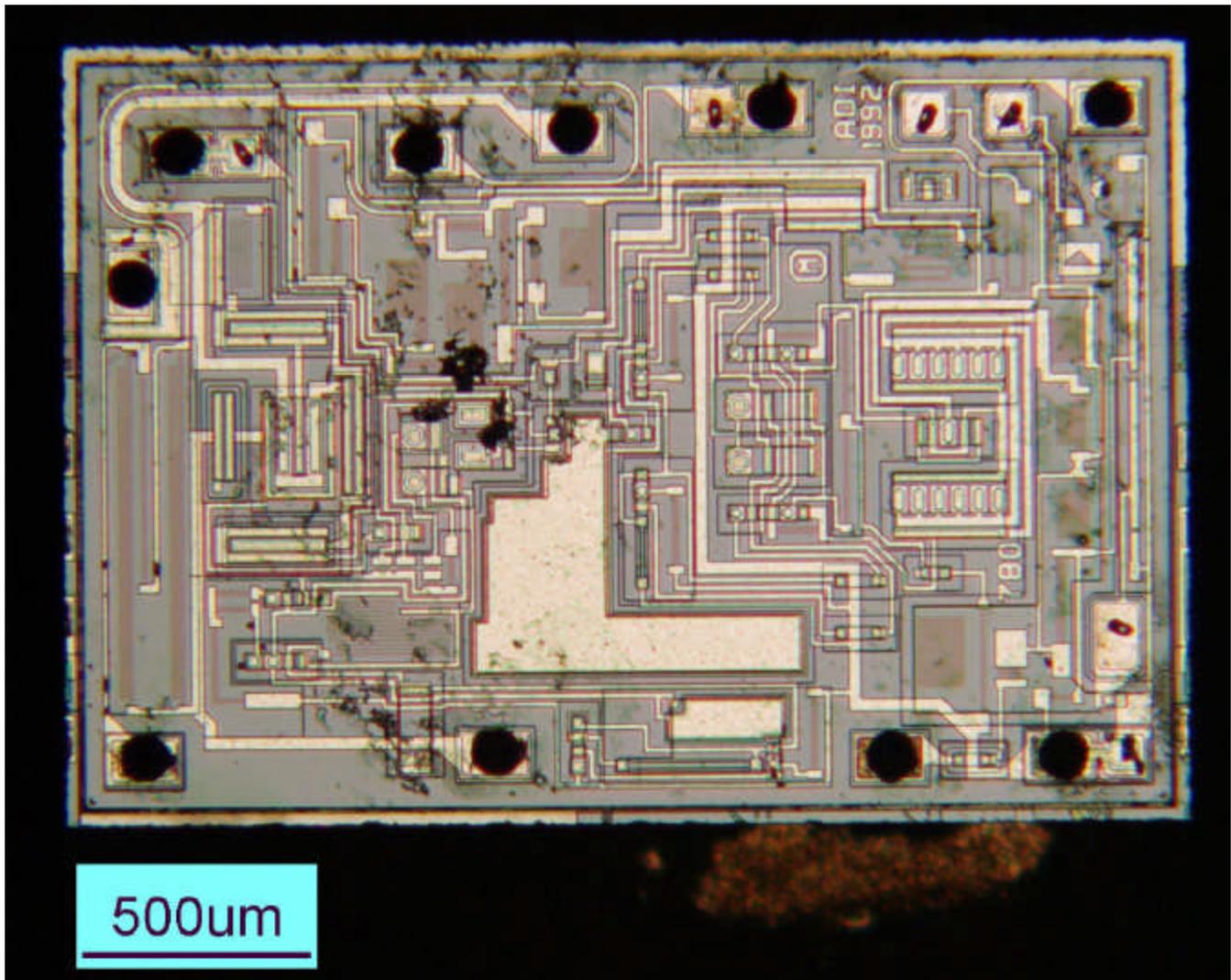


Figure 10. Overall optical image of SN D17 die. Like most of the glob-top devices investigated for SWIFT/BAT these devices did not deprocess very cleanly. Remnants of deprocessing are visible on this die. Deprocessing and inspection of most of the glob-topped devices required completely dissolving the package materials and ultrasonic cleaning of the dice.

Appended Photographs:

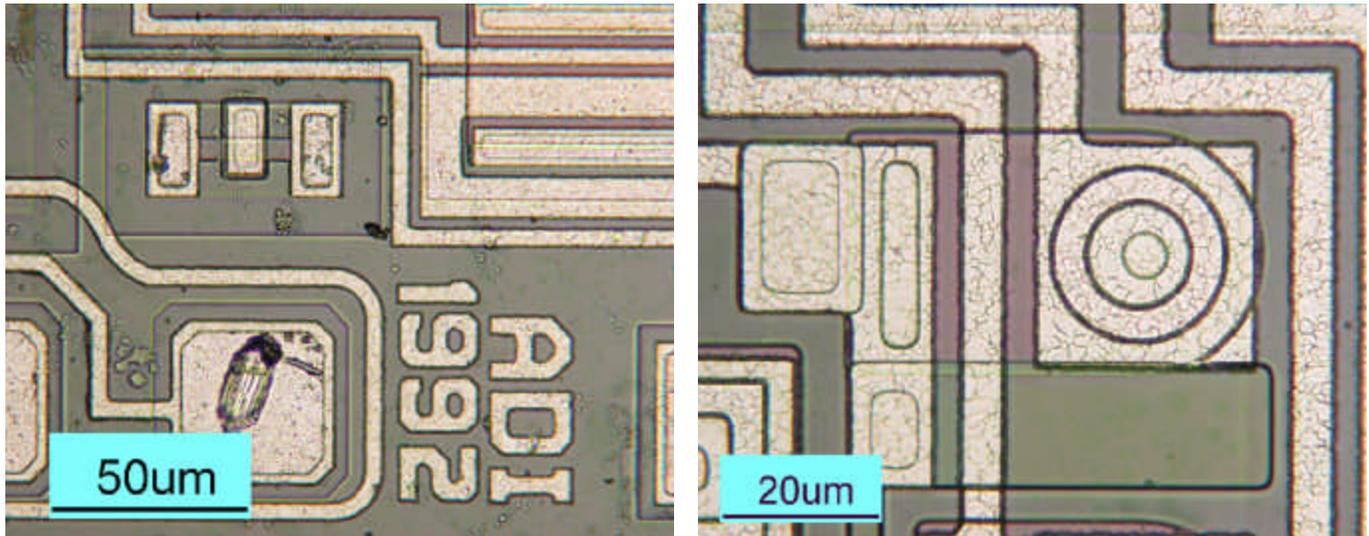


Figure 11. Optical micrograph images show typical features on SN D16 die.

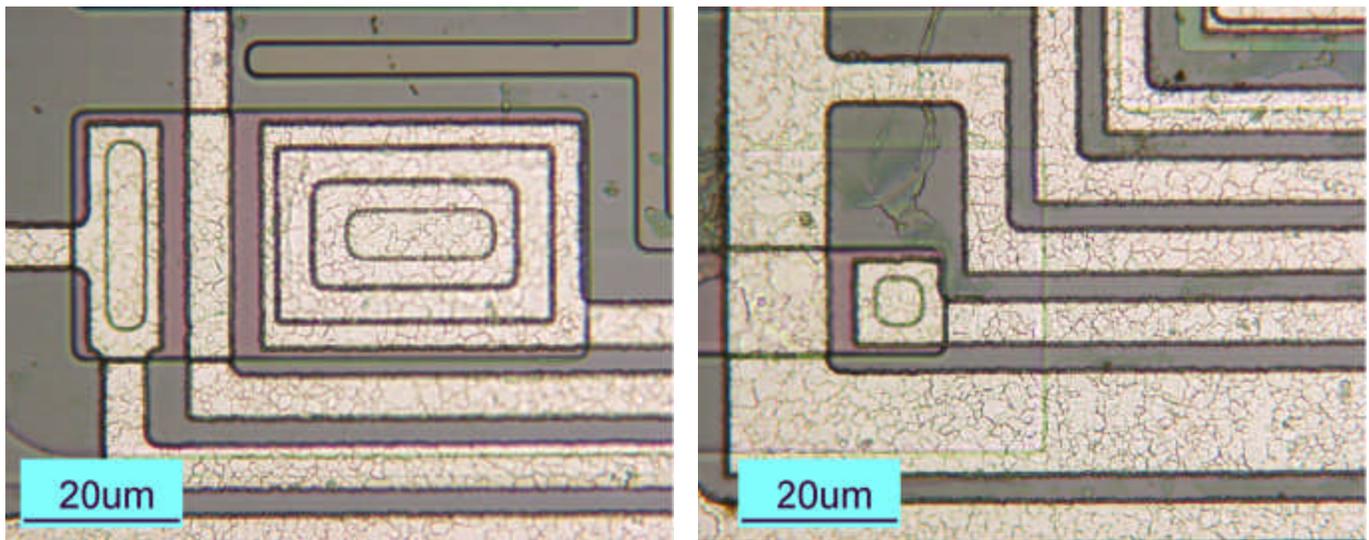


Figure 12. Optical micrograph images of SN D18.

Appended Photographs:

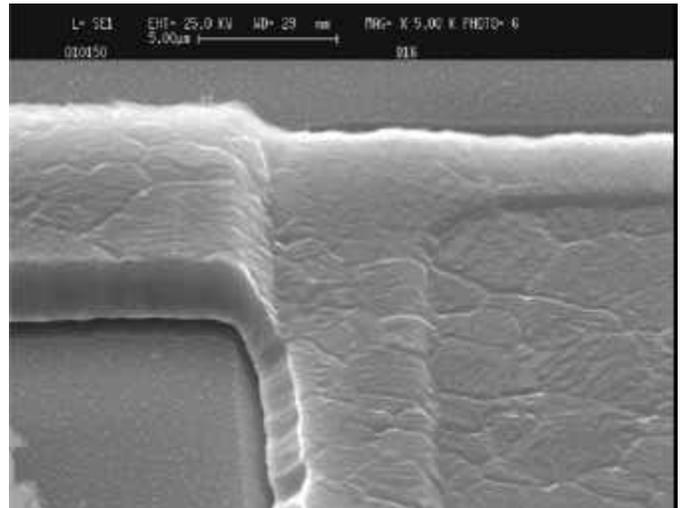
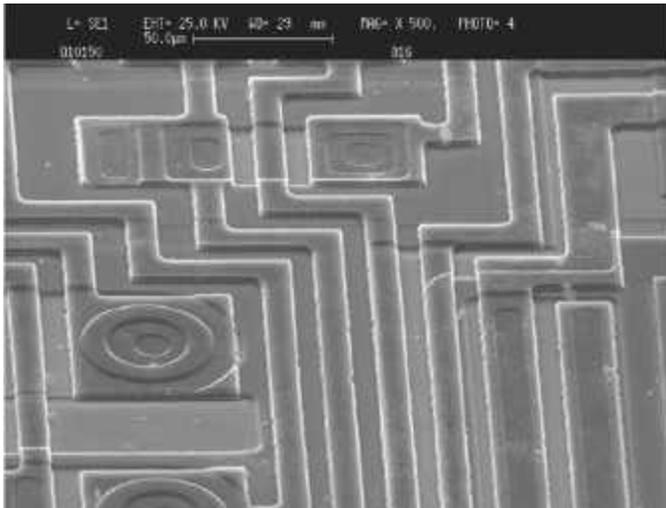


Figure 13. SEM micrographs of SN D16 show general metal features.

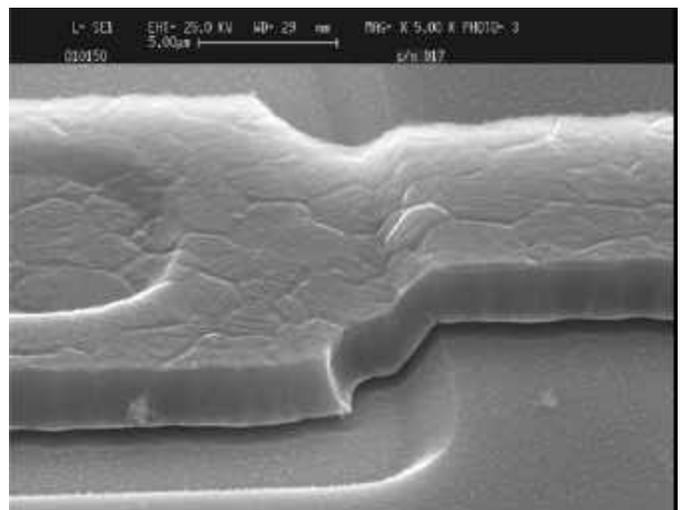
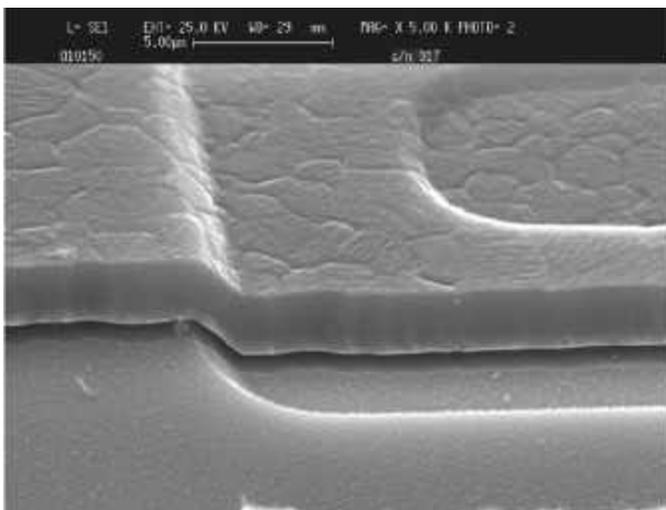


Figure 14. SEM micrographs of SN D17 show general metal features.